

10/501070

10 Rec'd PCT/PTO 06 JUN 2005

Customized PTO/USB/01 (08-03)

<b>DECLARATION FOR UTILITY OR DESIGN PATENT APPLICATION</b> <b>(37 CFR 1.63)</b>	Docket No.	P07444US01/BAS
	1 <sup>st</sup> Inventor	MACDONALD, D.M.
	COMPLETE IF KNOWN	
..... Declaration Submitted with Initial Filing	Appl. No.	10/501,070
<input checked="" type="checkbox"/> Declaration Submitted after Initial Filing	Filing Date	July 9, 2004

**I hereby declare that:**

Each inventor's residence, mailing address and citizenship are as stated below next to their name.

I believe the inventor(s) named below to be the original and first inventor(s) of the subject matter which is claimed and for which a patent is sought on the invention entitled:

**METHOD FOR BONDING THERMOPLASTIC OR THERMOSET POLYMERIC MATERIAL UTILIZING VOLTAGE APPLIED TO CONDUCTIVE MATERIAL**

the specification of which:

..... Is attached hereto

OR

..... ☒ was filed on January 9, 2002 as PCT International Application No. PCT/US03/00536,  
and (if applicable) was amended on .

I hereby state that I have reviewed and understand the contents of the above-identified specification, including the claims, as amended by any amendment specifically referred to above.

I acknowledge the duty to disclose information which is material to patentability as defined in 37 CFR 1.56, including for continuation-in-part applications, material information which became available between the filing date of the prior application and the national or PCT international filing date of the continuation-in-part application.

I hereby claim FOREIGN PRIORITY benefits under 35 USC 119(a)-(d) or (f), or 365(b) of any foreign application(s) for patent, inventor's certificate(s), or 365(a) of any PCT international application which designated at least one country other than the US, listed below and have also identified below, by checking the box, any foreign application for patent, inventor's certificate(s), or any PCT international application having a filing date before that of the application on which priority is claimed. ( Additional applications listed on supplemental sheet provided herewith )

Prior Foreign Appl. No.	Country	Filing Date (Day/Month/Year)	Priority Not Claimed

**Power Of Attorney & Correspondence Address Indication**

I hereby appoint the practitioners (of Stites &amp; Harbison PLLC) associated with

**CUSTOMER NUMBER 00881**

as my/our attorneys or agents to prosecute the application identified above, and to transact all business in the US Patent and Trademark Office connected therewith.

Please direct all correspondence to the noted Customer Number.

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under 18 USC 1001 and that such willful false statements may jeopardize the validity of the application or any patent issued thereon. ( Additional inventors named on supplemental sheet provided herewith )

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